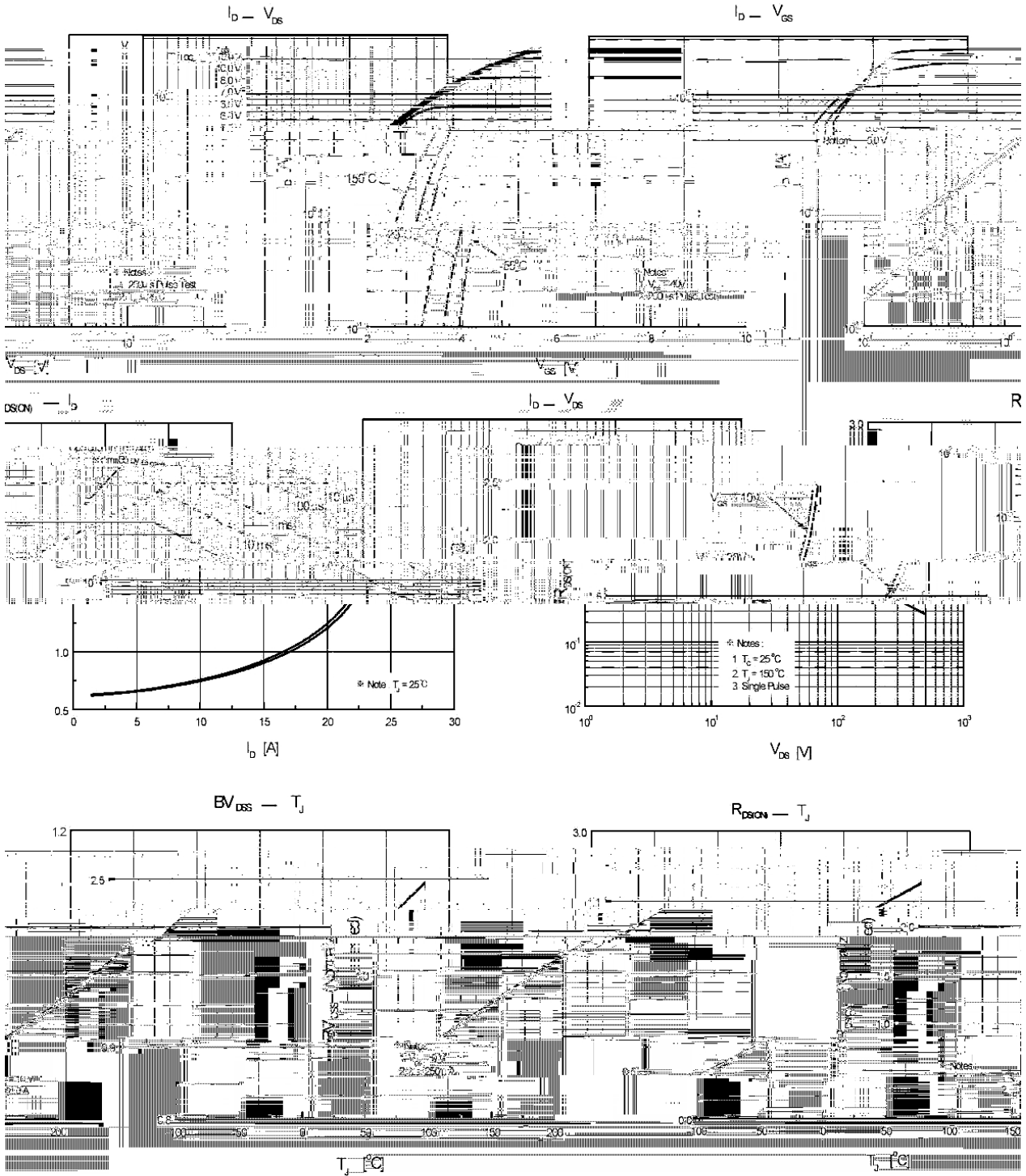


**BRD840**



**/ Electrical Characteristic Curve**



**BRD840**  
Rev.E Jan.-2025

**/ Marking Instructions**

BR  
840

**( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


Note:

- |   |           |             |   |
|---|-----------|-------------|---|
| 1 | 150 ~ 180 | 60 ~ 90sec; | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5     | 5±0.5sec;   | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 ~ 10    | /sec.       | 3. Cooling Speed: 2~10 /sec.            |

**/ Resistance to Soldering Heat Test Conditions**

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

**/ Packaging SPEC.**

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
TO-252	2,500	2	5,000	6	30,000	13 ×16	360×360×50	380×335×366

/ TUBE

Package Type	Units	Dimension (unit mm <sup>3</sup> )